

## **AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

### **LISTING OF CLAIMS**

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1. (Original) A semiconductor device comprising:
- a semiconductor wafer having a structure portion exposed on a surface thereof; and
- an adhesive sheet detachably attached to the surface of the semiconductor wafer and covering the structure portion, the adhesive sheet having a flat sheet member and an adhesive portion provided generally on an entire surface of the sheet member, the adhesive portion having a specific region facing the structure portion, the specific region having an adhesion smaller than that of a vicinal region of the adhesive portion surrounding the specific region.
2. (Original) The semiconductor device of claim 1, wherein the adhesive portion is made of UV setting adhesive, an adhesion of which is reduced by UV.
3. (Original) The semiconductor device of claim 1, wherein at least one of the adhesive sheet and the adhesive portion is made of a conductive material.
4. (Original) The semiconductor device of claim 1, wherein:
- the adhesive sheet has a flat surface contacting the semiconductor wafer; and

the specific region and the vicinal region of the adhesive portion form a part of the flat surface of the adhesive sheet.

5. (Original) The semiconductor device of claim 1, wherein the sheet member is made of a material that transmits UV.

6-28. (Withdrawn)

29. (Previously added) The semiconductor device of claim 1 wherein the specific region of the adhesive portion opposes a sensing element formed on the structural portion of the semiconductor wafer.

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